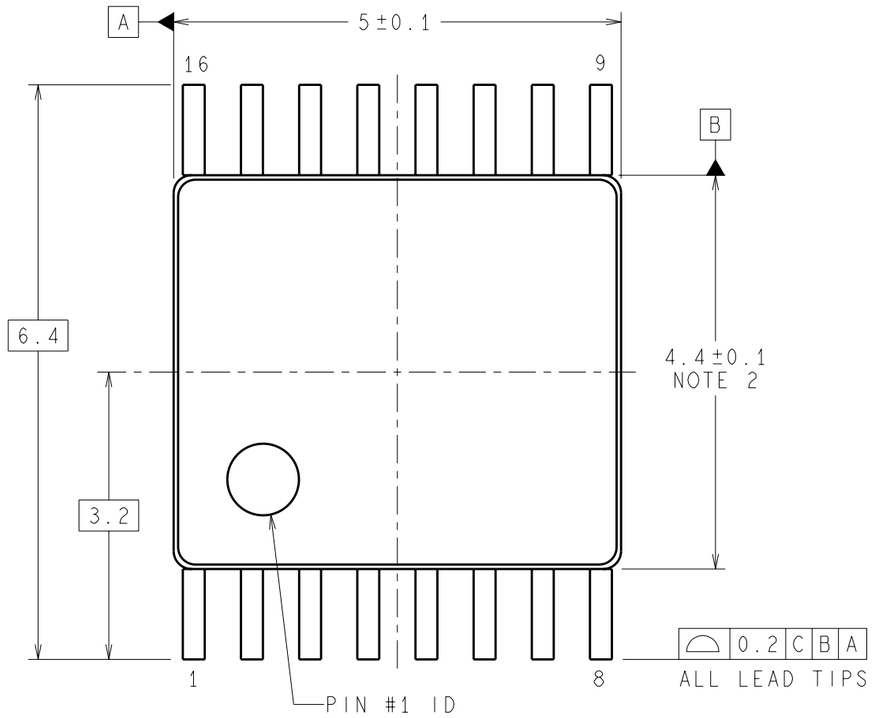
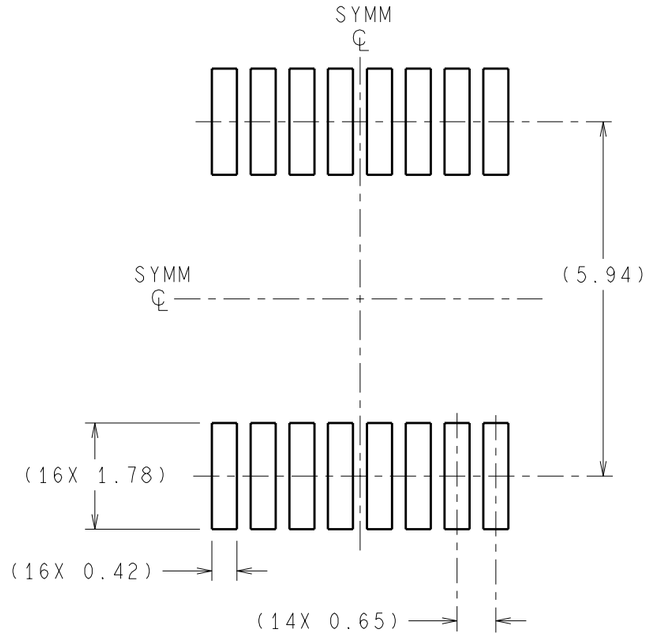
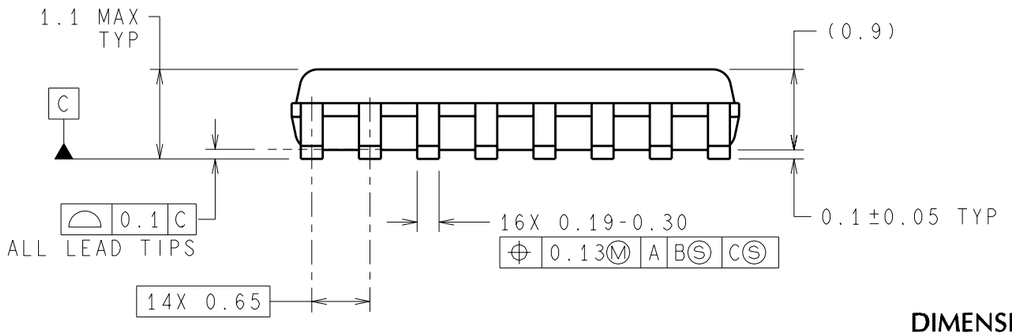
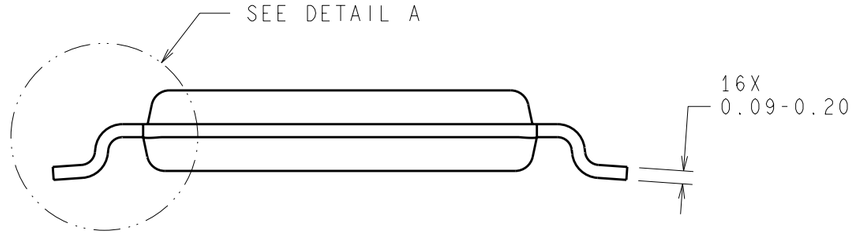
| REVISIONS | | | | |
|---|---|---|---|---|
| REV | DESCRIPTION | E.C.N. | DATE | BY/APP'D |
| C | REVISE & REDRAW ON PRO/E PER CURRENT STD; CORRECT DET CALLOUT FROM D TO A | 11104 | 08/29/1995 | MS/TC |
| D | REVISE PER CURRENT STD; ADD SOLDER & MOLD FLASH NOTES; UPDATE TITLE; CHG DWG FORMAT TO B SIZE | 1043 | 06/10/2003 | TL/RW |




**RECOMMENDED LAND PATTERN**

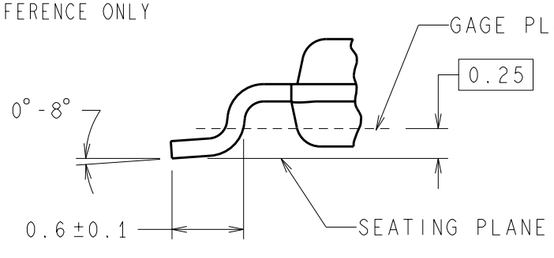



**DIMENSIONS ARE IN MILLIMETERS**
DIMENSIONS IN ( ) FOR REFERENCE ONLY

NOTES: UNLESS OTHERWISE SPECIFIED

1. FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
2. DIMENSION DOES NOT INCLUDE MOLD FLASH.
3. REFERENCE JEDEC REGISTRATION MO-153, VARIATION AB.




**DETAIL A**
TYPICAL

| APPROVALS | DATE |
|---|---|
| DRAWN MARTA SUCHY | 08/29/1995 |
| DFTG. CHK. MARTA SUCHY | 06/10/2003 |
| ENGR. CHK. RANDALL WALBERG | 06/10/2003 |

PROJECTION MM

National Semiconductor
2900 Semiconductor Dr., Santa Clara, CA 95052-8090

MOLDED TSSOP, JEDEC, 5x4.4x0.9mm BODY, 16 LD, 0.65mm PITCH

| SCALE | SIZE | DRAWING NUMBER | REV |
|---|---|---|---|
| NTS | B | (SC)MKT-MTC16 | D |

FORMERLY: N/A SHEET 1 of 1